

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/26/2022

Details for "REG1117-3.3"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
REG1117-3.3	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DCY 4	6.5x3.5x1.6	125.6

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.164179	100	1000000	0.130725	1307
Sub-Total			0.164179	100	1000000	0.130725	1307
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.55808	87.999975	880000	0.444364	4444
Thermoplastics	Epoxy	85954-11-6	0.076102	12.000025	120000	0.060595	606
Sub-Total			0.634182	100	1000000	0.504959	5050
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	57.49504	94.72	947200	45.779682	457797
Copper and Its Alloys	Iron	7439-89-6	0.1214	0.2	2000	0.096663	967
Nickel and Its Alloys	Nickel	7440-02-0	1.9424	3.2	32000	1.546611	15466
Other Inorganic Materials	Silicon	7440-21-3	0.53416	0.88	8800	0.425318	4253
Zinc and Its Alloys	Zinc	7440-66-6	0.607	1	10000	0.483316	4833
Sub-Total			60.7	100	1000000	48.33159	483316
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.150952	95.12	951200	0.916431	9164
Precious Metals	Gold	7440-57-5	0.009438	0.78	7800	0.007515	75
Precious Metals	Palladium	7440-05-3	0.04961	4.1	41000	0.039501	395
Sub-Total			1.21	100	1000000	0.963447	9634
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	51.678428	85.000001	850000	41.14828	411483
Other Plastics and Rubber	Carbon Black	1333-86-4	0.182394	0.299999	3000	0.145229	1452
Thermoplastics	Epoxy	85954-11-6	8.937328	14.7	147000	7.116232	71162
Sub-Total			60.79815	100	1000000	48.409741	484097
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.084225	100	1000000	1.659537	16595
Sub-Total			2.084225	100	1000000	1.659537	16595
Total			125.590736			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.